

BCP53 Series, SBCP53 Series

PNP Silicon Epitaxial Transistors

This PNP Silicon Epitaxial transistor is designed for use in audio amplifier applications. The device is housed in the SOT-223 package which is designed for medium power surface mount applications.

- High Current: 1.5 A
- NPN Complement is BCP56
- The SOT-223 Package can be soldered using wave or reflow. The formed leads absorb thermal stress during soldering, eliminating the possibility of damage to the die
- Device Marking:
BCP53T1 = AH
BCP53-10T1 = AH-10
BCP53-16T1 = AH-16
- AEC-Q101 Qualified and PPAP Capable
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	V_{CEO}	-80	Vdc
Collector-Base Voltage	V_{CBO}	-100	Vdc
Emitter-Base Voltage	V_{EBO}	-5.0	Vdc
Collector Current	I_C	1.5	Adc
Total Power Dissipation @ $T_A = 25^\circ\text{C}$ (Note 1.) Derate above 25°C	P_D	1.5 12	W mW/ $^\circ\text{C}$
Operating and Storage Temperature Range	T_J, T_{stg}	-65 to +150	$^\circ\text{C}$

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Ambient (surface mounted)	$R_{\theta JA}$	83.3	$^\circ\text{C}/\text{W}$
Lead Temperature for Soldering, 0.0625" from case Time in Solder Bath	T_L	260 10	$^\circ\text{C}$ s

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

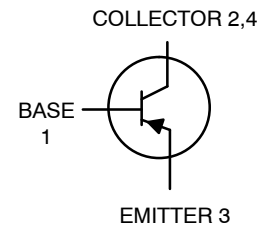
1. Device mounted on a glass epoxy printed circuit board 1.575 in. x 1.575 in. x 0.059 in.; mounting pad for the collector lead min. 0.93 sq. in.



ON Semiconductor®

<http://onsemi.com>

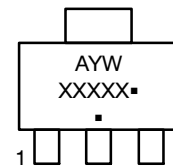
MEDIUM POWER HIGH CURRENT SURFACE MOUNT PNP TRANSISTORS



MARKING DIAGRAM



SOT-223
CASE 318E
STYLE 1



- A = Assembly Location
- Y = Year
- W = Work Week
- XXXXX = Specific Device Code
- = Pb-Free Package

(*Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping†
BCP53T1G	SOT-223 (Pb-Free)	1000 / Tape & Reel
SBCP53-10T1G	SOT-223 (Pb-Free)	1000 / Tape & Reel
BCP53-10T1G	SOT-223 (Pb-Free)	1000 / Tape & Reel
SBCP53-10T1G	SOT-223 (Pb-Free)	1000 / Tape & Reel
BCP53-16T1G	SOT-223 (Pb-Free)	1000 / Tape & Reel
SBCP53-16T1G	SOT-223 (Pb-Free)	1000 / Tape & Reel
BCP53-16T3G	SOT-223 (Pb-Free)	4000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

BCP53 Series, SBCP53 Series

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristics	Symbol	Min	Typ	Max	Unit
-----------------	--------	-----	-----	-----	------

OFF CHARACTERISTICS

Collector-Base Breakdown Voltage ($I_C = -100 \mu\text{A}$, $I_E = 0$)	$V_{(BR)CBO}$	-100	-	-	Vdc
Collector-Emitter Breakdown Voltage ($I_C = -1.0 \text{mA}$, $I_B = 0$)	$V_{(BR)CEO}$	-80	-	-	Vdc
Collector-Emitter Breakdown Voltage ($I_C = -100 \mu\text{A}$, $R_{BE} = 1.0 \text{k}\Omega$)	$V_{(BR)CER}$	-100	-	-	Vdc
Emitter-Base Breakdown Voltage ($I_E = -10 \mu\text{A}$, $I_C = 0$)	$V_{(BR)EBO}$	-5.0	-	-	Vdc
Collector-Base Cutoff Current ($V_{CB} = -30 \text{Vdc}$, $I_E = 0$)	I_{CBO}	-	-	-100	nA
Emitter-Base Cutoff Current ($V_{EB} = -5.0 \text{Vdc}$, $I_C = 0$)	I_{EBO}	-	-	-10	μA

ON CHARACTERISTICS

DC Current Gain ($I_C = -5.0 \text{mA}$, $V_{CE} = -2.0 \text{Vdc}$) All Part Types ($I_C = -150 \text{mA}$, $V_{CE} = -2.0 \text{Vdc}$) BCP53, SBCP53 BCP53-10, SBCP53-10 BCP53-16, SBCP53-16 ($I_C = -500 \text{mA}$, $V_{CE} = -2.0 \text{Vdc}$) All Part Types	h_{FE}	25	-	-	-
		40	-	250	
		63	-	160	
		100	-	250	
		25	-	-	
Collector-Emitter Saturation Voltage ($I_C = -500 \text{mA}$, $I_B = -50 \text{mA}$)	$V_{CE(sat)}$	-	-	-0.5	Vdc
Base-Emitter On Voltage ($I_C = -500 \text{mA}$, $V_{CE} = -2.0 \text{Vdc}$)	$V_{BE(on)}$	-	-	-1.0	Vdc

DYNAMIC CHARACTERISTICS

Current-Gain - Bandwidth Product ($I_C = -10 \text{mA}$, $V_{CE} = -5.0 \text{Vdc}$, $f = 35 \text{MHz}$)	f_T	-	50	-	MHz
--	-------	---	----	---	-----

BCP53 Series, SBCP53 Series

TYPICAL CHARACTERISTICS

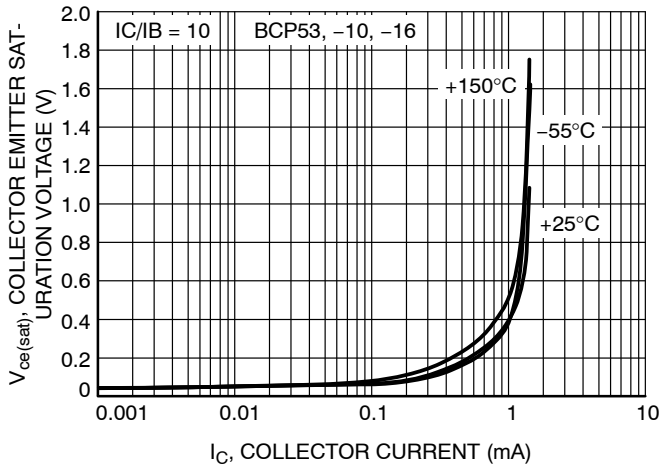


Figure 1. Collector Emitter Saturation Voltage vs. Collector Current

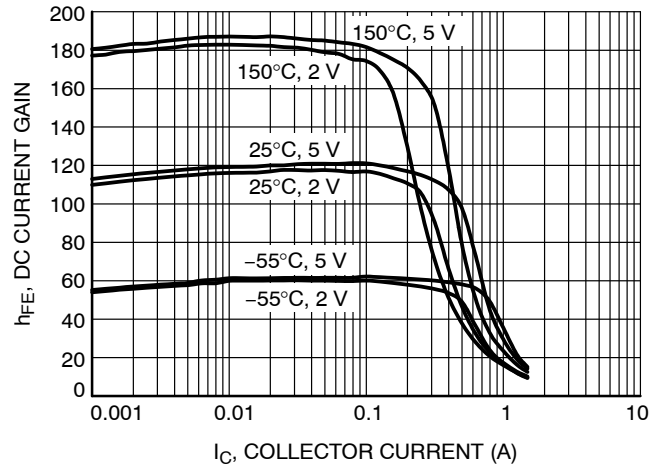


Figure 2. DC Current Gain vs. Collector Current (BCP53)

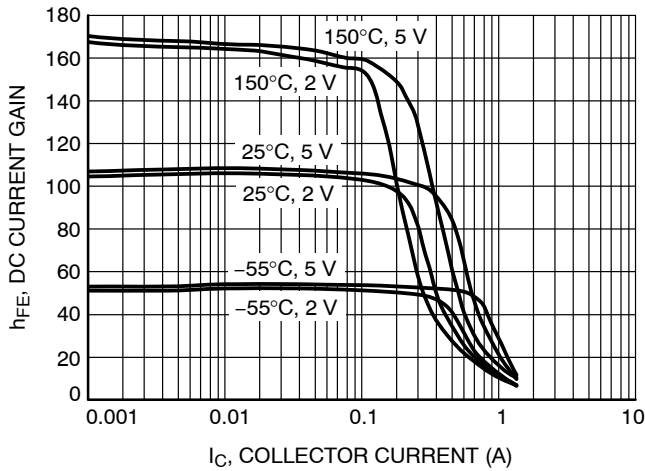


Figure 3. DC Current Gain vs. Collector Current (BCP53-10)

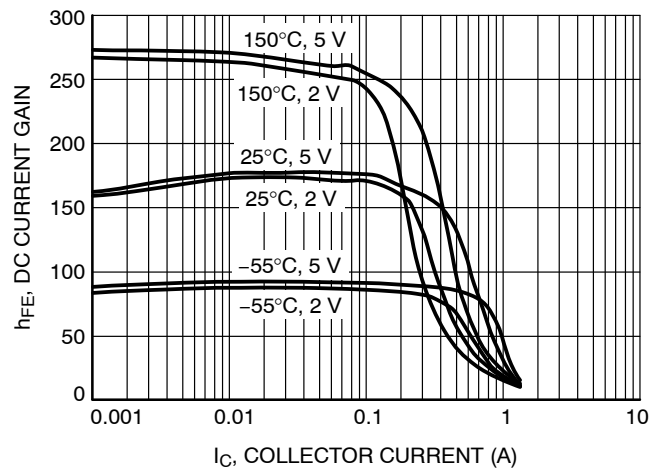


Figure 4. DC Current Gain vs. Collector Current (BCP53-16)

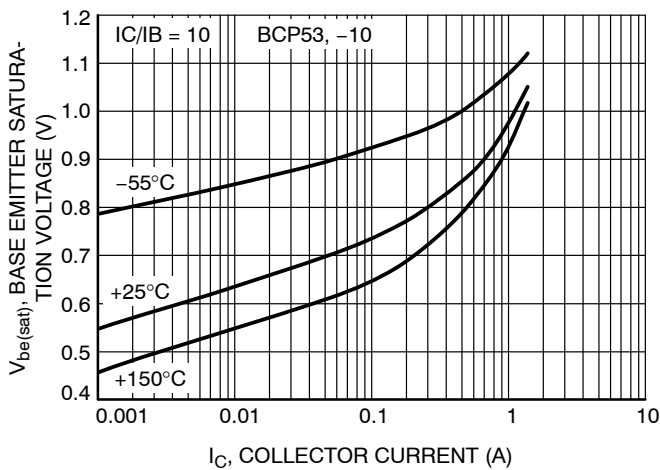


Figure 5. BCP53, -10 Base Emitter Saturation Voltage vs. Collector Current

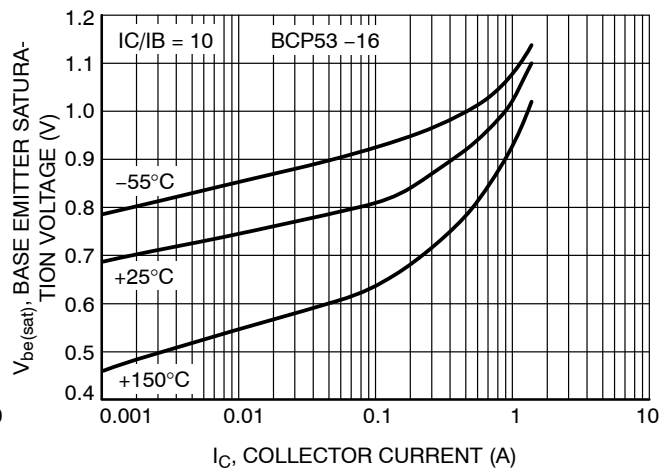


Figure 6. BCP53-16 Base Emitter Saturation Voltage vs. Collector Current

BCP53 Series, SBCP53 Series

TYPICAL CHARACTERISTICS

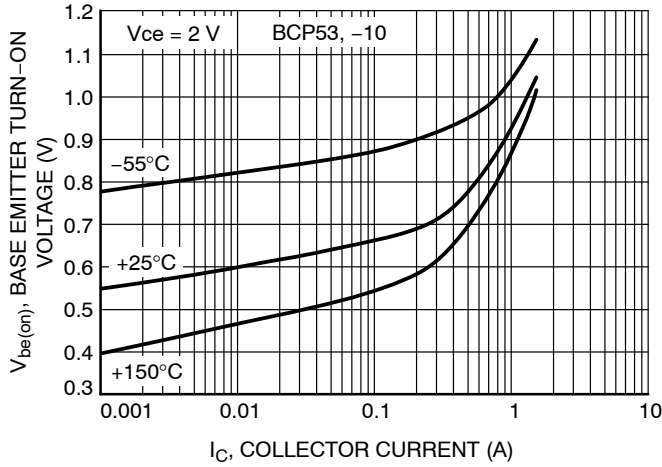


Figure 7. BCP53, -10 Base Emitter Turn-On Voltage vs. Collector Current $V_{BE(on)}$

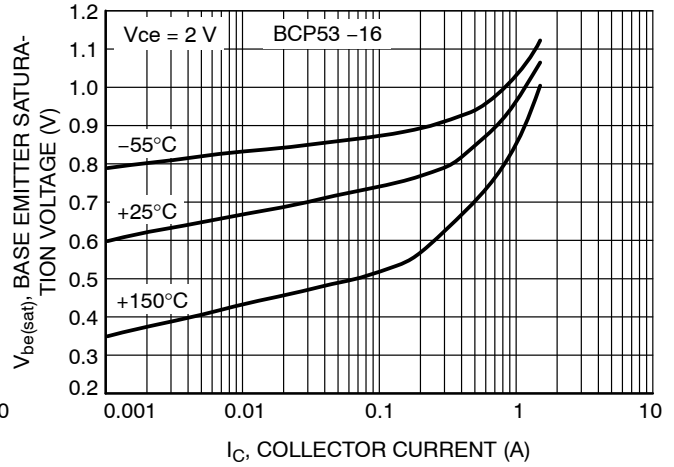


Figure 8. BCP53-16 Base Emitter Turn-On Voltage vs. Collector Current

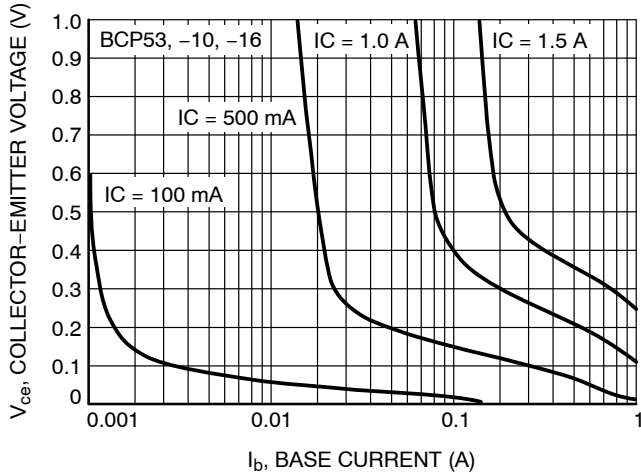


Figure 9. BCP53, -10, -16 Saturation Region

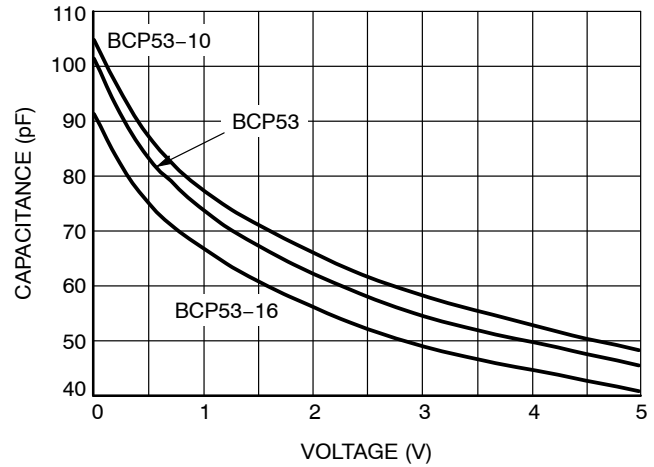


Figure 10. Input Capacitance

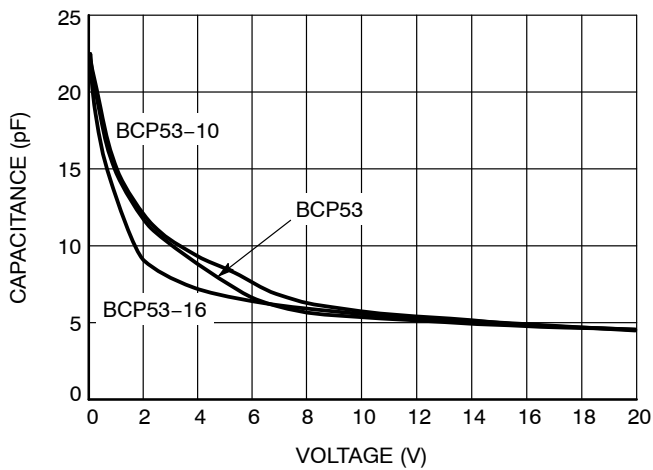


Figure 11. Output Capacitance

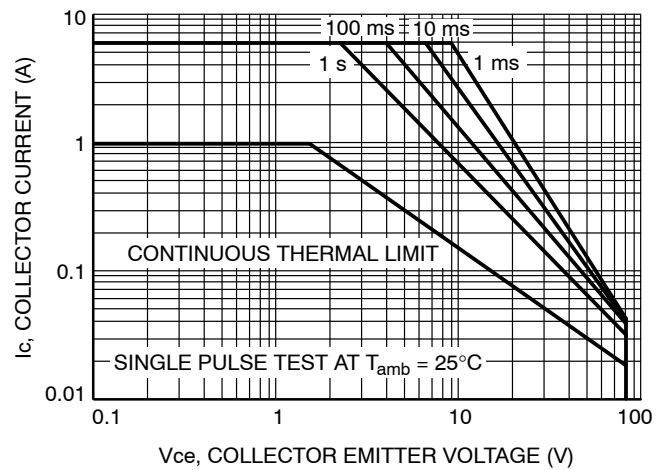
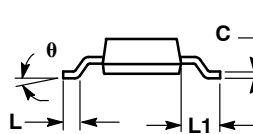
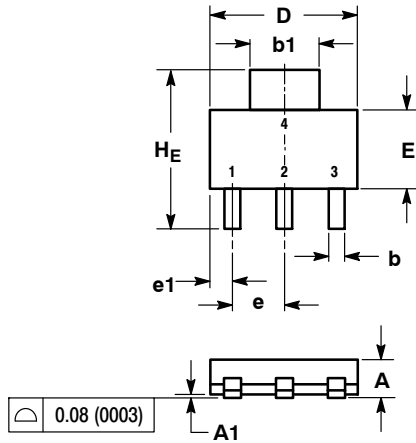


Figure 12. Standard Operating Area

BCP53 Series, SBCP53 Series

PACKAGE DIMENSIONS

SOT-223 (TO-261)
CASE 318E-04
ISSUE N

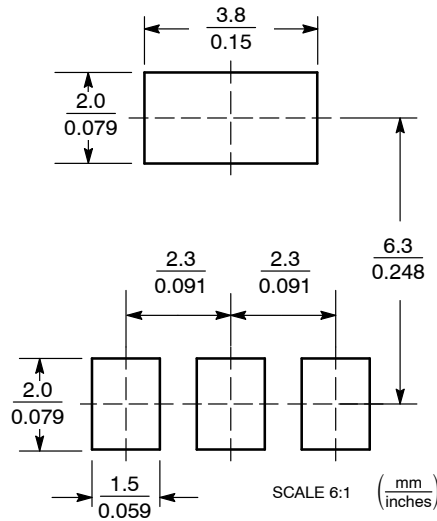


NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCH

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.50	1.63	1.75	0.060	0.064	0.068
A1	0.02	0.06	0.10	0.001	0.002	0.004
b	0.60	0.75	0.89	0.024	0.030	0.035
b1	2.90	3.06	3.20	0.115	0.121	0.126
c	0.24	0.29	0.35	0.009	0.012	0.014
D	6.30	6.50	6.70	0.249	0.256	0.263
E	3.30	3.50	3.70	0.130	0.138	0.145
e	2.20	2.30	2.40	0.087	0.091	0.094
e1	0.85	0.94	1.05	0.033	0.037	0.041
L	0.20	---	---	0.008	---	---
L1	1.50	1.75	2.00	0.060	0.069	0.078
HE	6.70	7.00	7.30	0.264	0.276	0.287
θ	0°	-	10°	0°	-	10°

STYLE 1:
PIN 1. BASE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Literature Distribution Center for ON Semiconductor
P.O. Box 5163, Denver, Colorado 80217 USA
Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada
Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com
Order Literature: <http://www.onsemi.com/orderlit>
For additional information, please contact your local Sales Representative

Компания «Life Electronics» занимается поставками электронных компонентов импортного и отечественного производства от производителей и со складов крупных дистрибьюторов Европы, Америки и Азии.

С конца 2013 года компания активно расширяет линейку поставок компонентов по направлению коаксиальный кабель, кварцевые генераторы и конденсаторы (керамические, пленочные, электролитические), за счёт заключения дистрибьюторских договоров

Мы предлагаем:

- Конкурентоспособные цены и скидки постоянным клиентам.
- Специальные условия для постоянных клиентов.
- Подбор аналогов.
- Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.
- Приемлемые сроки поставки, возможна ускоренная поставка.
- Доставку товара в любую точку России и стран СНГ.
- Комплексную поставку.
- Работу по проектам и поставку образцов.
- Формирование склада под заказчика.
- Сертификаты соответствия на поставляемую продукцию (по желанию клиента).
- Тестирование поставляемой продукции.
- Поставку компонентов, требующих военную и космическую приемку.
- Входной контроль качества.
- Наличие сертификата ISO.

В составе нашей компании организован Конструкторский отдел, призванный помогать разработчикам, и инженерам.

Конструкторский отдел помогает осуществить:

- Регистрацию проекта у производителя компонентов.
- Техническую поддержку проекта.
- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.



Тел: +7 (812) 336 43 04 (многоканальный)

Email: org@lifeelectronics.ru